

11-21-2001

COVER SHEET
YU.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 08245.0029
Attorney Customer Number: 22,852To the Honorable Comr
Please record the attach

101900003

ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):
Jeong Hee OH

2. Name and address of receiving party(ies):

Name: Hynix Semiconductor Inc.

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Internal Address:

3. Nature of conveyance:

Street Address: San 136-1, Ami-ri, Bubal-eub,
Ich'on, Kyoungki-do, Korea☐ Assignment ☐ Merger

City:

☐ Security Agreement ☐ Change of Name

State:

Zip Code:

☒ Other: Correction of error in Recordation Form Cover
Sheet (form PTO-1594)

Additional name(s) & Address(es) attached?

Execution Date: June 5, 2001

☐ Yes☒ No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application:

A. Patent Application Number(s):

09/891,193

B. Patent Number(s):

Additional numbers attached?

☐ Yes☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

6. Total number of applications and registrations involved:
1

7. Total fee (37 CFR 3.41): \$40

☒ Enclosed (Please charge deficiency to deposit account)☐ Authorized to be charged to deposit accountInternal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT
& DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington, D.C.

State: Zip: 20005-3315

8. Deposit Account No.: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman

Reg. No. 25,961

Signature

November 16, 2001

Date

Total number of pages including cover sheet, attachments and documents: 5

11/20/2001 TBIAZI 00000068 09891193

01 FC:581

40.00 DP

PATENT
REEL: 012310 FRAME: 0079

FORM PTO-1594
1-31-92

07-05-2001

HEET

U.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 08245.0029
CUSTOMER NUMBER: 22,852

To the Honorable Commissioner of F
Please record the attached original d



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ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):

Jeong Hee OH

06/24/01

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other

09/891193

Execution Date: June 5, 2001

2. Name and address of receiving party(ies):

Name: Hynix Semiconductor Inc.

Internal Address:

Street Address: San 136-1, Ami-ri, Babal-eub,
Ich'on, Kyongki-do, Korea

City:

State:

Zip Code:

Additional name(s) & Address(es) attached?

☐ Yes ☒ No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application: June 5, 2001

A. Patent Application Number(s):

6/28/2001 NDANTE1 00000011 09891193

3 PD:581

40.00 OP

B. Patent Number(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT
& DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington

State: DC Zip: 20005-3315

6. Total number of applications and registrations involved:
1

7. Total fee (37 CFR 3.41): \$40

☒

Enclosed (Please charge deficiency to deposit account)

☐

Authorized to be charged to deposit account

8. Deposit account number: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman

Reg. No. 25,961

Signature

June 26, 2001

Date

Total number of pages including cover sheet, attachments and documents: 2

PATENT

REEL: 012310 FRAME: 0080

SOLE/JOINT INVENTION
(Worldwide Rights)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled: METHOD FOR MAKING SOI MOSFETs

[TITLE OF INVENTION]

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on [], 20__ (Serial No. _____); and

WHEREAS, [Hynix Semiconductor Inc.], a corporation of [Republic of Korea] whose post office address is [San 136-1, Ami-ri, Bubal-eub, Ich'on, Kyungki-do, Korea] (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional application Serial No. _____, filed _____ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

County of Korea)

)

ss.

Seocho-gu, Seoul, Korea]

State of Korea)

[Jeong Hee OH]

[207-405, Shinpanpo 4th Apt., 70, Chamwon-dong,

By:



Date:

June 5, 2001

Subscribed and sworn to before me this ____ day of _____, 20__
_____, Notary Public

FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P. WASHINGTON, D.C.

FHFGD June 97

PATENT

RECORDED: 11/16/2001

REEL: 012310 FRAME: 0081